

December 2013

# FFB3906 / FMB3906 / MMPQ3906 PNP Multi-Chip General-Purpose Amplifier

### **Description**

This device is designed for general-purpose amplifier and switching applications at collector currents of 10  $\mu$ A to 100 mA. Sourced from Process 66.

### **Block Diagram**

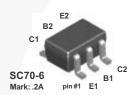


Figure 1. FFB3906 Device Package

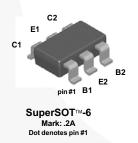


Figure 3. FMB3906 Device Package

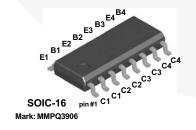


Figure 5. MMPQ3906 Device Package

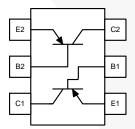


Figure 2. FFB3906 Internal Connections

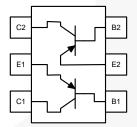


Figure 4. FMB3906 Internal Connections

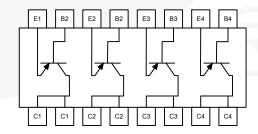


Figure 6. MMPQ3906 Internal Connections

## **Ordering Information**

Part Number	Top Mark	Package	Packing Method
FFB3906	.2A	SC70 6L	Tape and Reel
FMB3906	.2A	SSOT 6L	Tape and Reel
MMPQ3906	MMPQ3906	SOIC 16L	Tape and Reel

### Absolute Maximum Ratings(1)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^{\circ}$ C unless otherwise noted.

Symbol	Parameter	Value	Unit
V <sub>CEO</sub>	Collector-Emitter Voltage	-40	V
$V_{CBO}$	Collector-Base Voltage	-40	V
V <sub>EBO</sub>	Emitter-Base Voltage	-5	V
I <sub>C</sub>	Collector Current - Continuous	-200	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

#### Note:

1. These ratings are based on a maximum junction temperature of 150°C. These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty cycle operations.

### Thermal Characteristics(2)

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Max.			Unit
Syllibol	Farameter	FFB3906	FMB3906	MMPQ3906	Onit
D	Total Device Dissipation	300	700	1,000	mW
$P_{D}$	Derate Above 25°C	2.4	5.6	8.0	mW/°C
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient	415	180		°C/W
	Thermal Resistance, Junction to Ambient, Effective 4 Die			125	°C/W
	Thermal Resistance, Junction to Ambient, Each Die			240	°C/W

#### Note:

2. PCB size: FR-4 76 x 114 x 0.6T mm<sup>3</sup> (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

### **Electrical Characteristics**

Values are at  $T_A = 25^{\circ}C$  unless otherwise noted.

Symbol	Para	meter	Conditions	Min.	Тур.	Max.	Unit	
Off Charac	cteristics				•			
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage <sup>(3)</sup>		$I_C = -1.0 \text{ mA}, I_B = 0$	-40			V	
V <sub>(BR)CBO</sub>	Collector-Base Brea	akdown Voltage	$I_C = -10 \mu A, I_E = 0$	-40			V	
V <sub>(BR)EBO</sub>	Emitter-Base Break	down Voltage	$I_E = -10 \mu A, I_C = 0$	-5.0			V	
I <sub>BL</sub>	Base Cut-Off Currer	nt	$V_{CE} = -30 \text{ V}, V_{BE} = 3.0 \text{ V}$			-50	nA	
I <sub>CEX</sub>	Collector Cut-Off Cu	urrent	V <sub>CE</sub> = -30 V, V <sub>BE</sub> = 3.0 V			-50	nA	
On Characteristics								
		FFB3906, FMB3906	- 0.1 m \ \/ - 1.0 \/	60				
		MMPQ3906	$I_C = -0.1 \text{ mA}, V_{CE} = -1.0 \text{ V}$	40				
	DC Current Gain <sup>(3)</sup>	FFB3906, FMB3906	1 10 1 1/ 10 1/	80				
h		MMPQ3906	$I_C = -1.0 \text{ mA}, V_{CE} = -1.0 \text{ V}$	60				
h <sub>FE</sub>		FFB3906, FMB3906	L = 10 m/s \/ = 10 \/	100		300		
		MMPQ3906	$I_C = 10 \text{ mA}, V_{CE} = -1.0 \text{ V}$	75				
		All Devices	$I_C = -50 \text{ mA}, V_{CE} = -1.0 \text{ V}$	60				
		All Devices	$I_C = -100 \text{ mA}, V_{CE} = -1.0 \text{ V}$	30				
V	Collector Emitter Sc	struction Valters	$I_C = -10 \text{ mA}, I_B = -1.0 \text{ mA}$			-0.25	V	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage		$I_C = -50 \text{ mA}, I_B = -5.0 \text{ mA}$			-0.40	V	
	Base-Emitter Saturation Voltage		$I_C = -10 \text{ mA}, I_B = -1.0 \text{ mA}$	-0.65		-0.85	V	
V <sub>BE(sat)</sub> Base-Emitter Satura		alion voltage	$I_C = -50 \text{ mA}, I_B = -5.0 \text{ mA}$			-0.95		
Small-Signal Characteristics (MMPQ3906 Only)								
$f_{T}$	Current Gain-Bandwidth Product		$I_C$ = -10 mA, $V_{CE}$ = -20 V, f = 100 MHz		200		MHz	
C <sub>ob</sub>	Output Capacitance		$V_{CB} = -5.0 \text{ V}, I_{E} = 0,$ f = 140 kHz		4.5		pF	
C <sub>ib</sub>	Input Capacitance		$V_{EB} = -0.5 \text{ V}, I_{C} = 0,$ f = 140 kHz		10		pF	

### Note:

3. Pulse test: pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2.0%.

### **Typical Performance Characteristics**

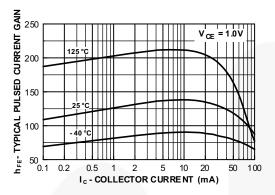


Figure 7. Typical Pulsed Current Gain vs. Collector Current

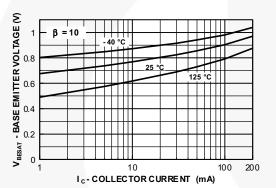


Figure 9. Base-Emitter Saturation Voltage vs.
Collector Current

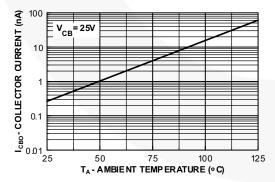


Figure 11. Collector Cut-Off Current vs.
Ambient Temperature

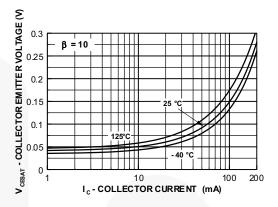


Figure 8. Collector-Emitter Saturation Voltage vs.
Collector Current

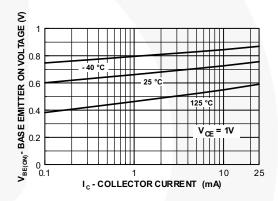


Figure 10. Base-Emitter On Voltage vs. Collector Current

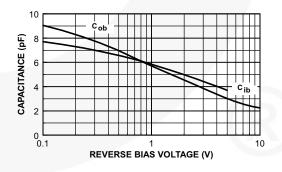


Figure 12. Common-Base Open Circuit Input and Output Capacitance vs. Reverse Bias Voltage

## **Typical Performance Characteristics** (Continued)

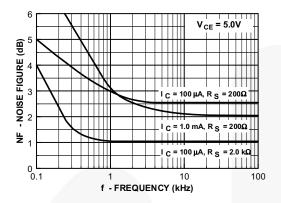


Figure 13. Noise Figure vs. Frequency

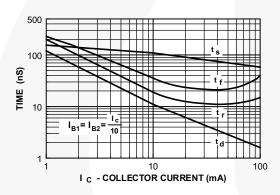


Figure 15. Switching Times vs. Collector Current

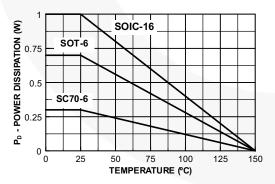


Figure 17. Power Dissipation vs. Ambient Temperature

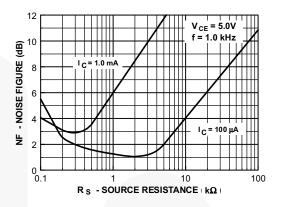


Figure 14. Noise Figure vs. Source Resistance

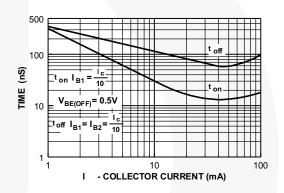


Figure 16. Turn-On and Turn-Off Times vs. Collector Current

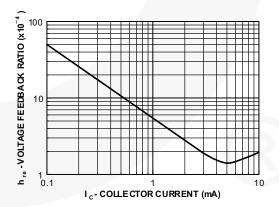


Figure 18. Voltage Feedback Ratio

## **Typical Performance Characteristics** (Continued)

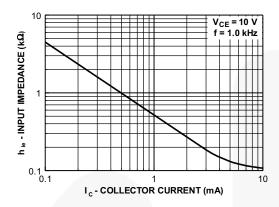


Figure 19. Input Impedance

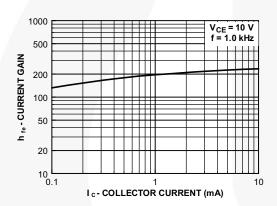


Figure 21. Current Gain

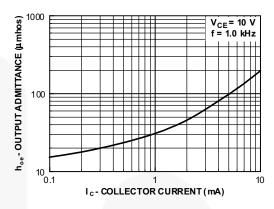


Figure 20. Output Admittance

### **Physical Dimensions**

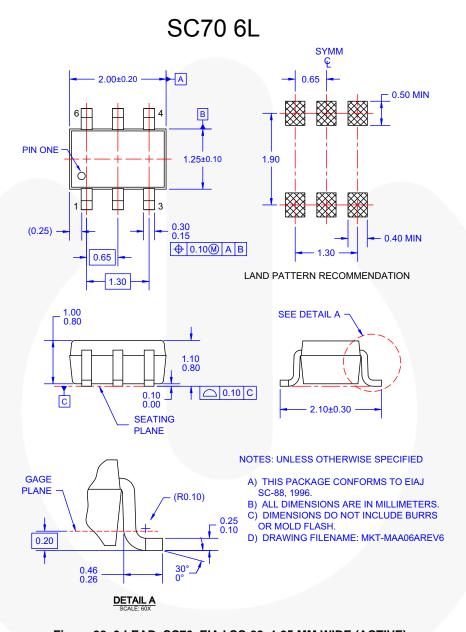


Figure 22. 6-LEAD, SC70, EIAJ SC-88, 1.25 MM WIDE (ACTIVE)

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### Physical Dimensions (Continued)

## SSOT 6L

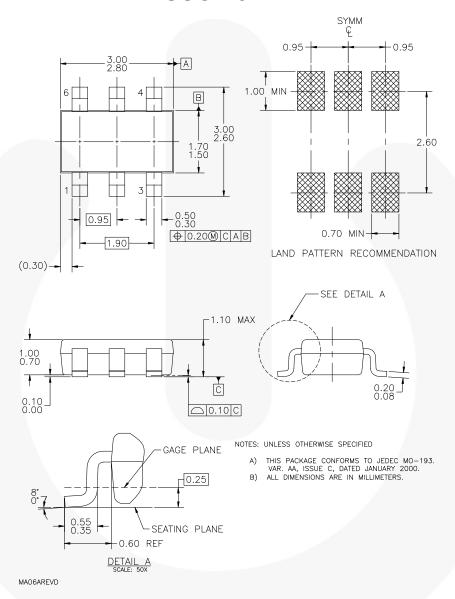


Figure 23. 6-LEAD, SUPERSOT-6, JEDEC MO-193, 1.6 MM WIDE (ACTIVE)

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### Physical Dimensions (Continued)

## SO 16L NB

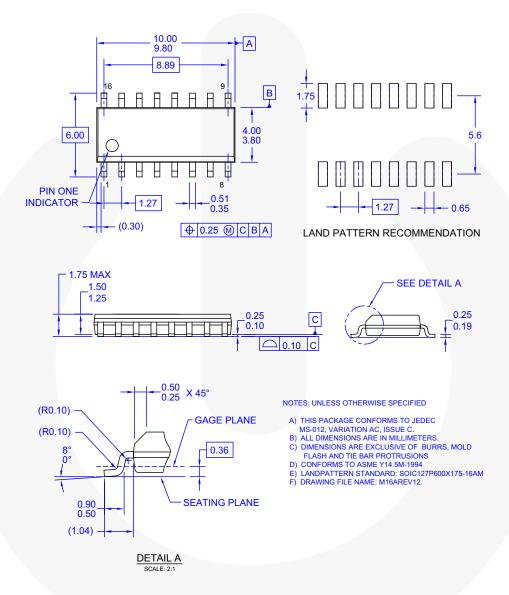


Figure 24. 16-LEAD, SOIC, JEDEC MS-012, 0.150 inch, NARROW BODY (ACTIVE)

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